#### ECEN474: (Analog) VLSI Circuit Design Fall 2011

#### Lecture 1: Introduction



Sebastian Hoyos Analog & Mixed-Signal Center Texas A&M University

#### Analog Circuit Sequence



## Why is Analog Important?



- Naturally occurring signals are analog
- Analog circuits are required to amplify and condition the signal for further processing
- Performance of analog circuits often determine whether the chip works or not
- Examples
  - Sensors and actuators (imagers, MEMS)
  - RF transceivers
  - Microprocessor circuits (PLL, high-speed I/O, thermal sensor)

## **Integrated Circuits**

[Bohr ISSCC 2009]



- 4-core Microprocessor (45nm CMOS)
  - Mostly Digital
    - Noteable analog blocks
      - PLL, I/O circuits, thermal sensor



[Sowlati ISSCC 2009]

- Cellular Transceiver (0.13µm CMOS)
  - Considerable analog & digital
- Instrumentation Amplifier (0.5µm CMOS)
  - Mostly Analog
  - Some Digital Control Logic

#### [Pertijs ISSCC 2009]



### The Power of CMOS Scaling





- Scaling transistor dimensions allows for improved performance, reduced power, and reduced cost/transistor
- Assuming you can afford to build the fab
  - 32nm CMOS fab ~3-4 BILLION dollars

## **Course Topics**

- CMOS technology
  - Active and passive devices
  - Layout techniques
- MOS circuit building blocks
  - Single-stage amplifiers, current mirrors, differential pairs
- Amplifiers and advanced circuit techiques

#### Course Goals

- Learn analog CMOS design approaches
  - Specification ⇒ Circuit Topology ⇒ Circuit Simulation ⇒ Layout ⇒ Fabrication
- Understand CMOS technology from a design perspective
  - Device modeling and layout techniques
- Use circuit building blocks to construct moderately complex analog circuits
  - Multi-stage amplifiers, filters, simple data converters, ...

#### Administrative

- Instructor:
  - Sebastian Hoyos
  - 315D WERC Bldg., 862-4253, hoyos@ece.tamu.edu
  - Office hours: MW 10:30am-12pm
- Lectures: MWF 9:10am-10am, ZACH 223B
- Class web page
  - http://www.ece.tamu.edu/~hoyos/ecen474.html

#### **Class Material**

- Textbook: *Design of Analog CMOS Integrated Circuits*, B. Razavi, McGraw-Hill, 2001
- References
  - Analysis and Design of Analog Integrated Circuits, P. Gray, R. Meyer, P. Hurst, and S. Lewis, John Wiley & Sons, 4<sup>th</sup> Edition, 2003.
  - Technical Papers
- Class notes
  - Posted on the web and will hand out hard copies in class

# Grading

- Exams (60%)
  - Three midterm exams (20% each)
- Homework (10%)
  - Collaboration is allowed, but independent simulations and write-ups
  - Need to setup CADENCE simulation environment
  - Due at beginning of class
  - No late homework will be graded
- Laboratory (20%)
- Final Project (10%)
  - Groups of 1-2 students
  - Report and PowerPoint presentation required

## Preliminary Schedule

Торіс	Week
I. Introduction and MOS models	- Week 1-4
II. CMOS Technologies and Layouts	
Review Session	Sep. 28
1 <sup>st</sup> Exam	Sep. 30
III. Current Mirrors and Differential Pairs	Week 5-9
IV. Voltage References and Differential Pairs	
V. OTA Design (Part 1)	
Review Session	Nov. 2
2 <sup>nd</sup> Exam	Nov. 4
VI. OTA Design (Part 2)	Week 10-14
VII. Miller OpAmp Design	
VIII. Advanced Topics	
Review Session	Nov. 30
3 <sup>rd</sup> Exam	<b>Dec. 2</b>
Project Report Due	<b>Dec.</b> 7
Project Presentation	Dec. 12

Dates may change with reasonable notice

## Reading

Razavi's CMOS Book Chapter 1 and 2

## CMOS Technology Overview

- MOS Transistors
- Interconnect
- Diodes
- Resistors
- Capacitors
- Inductors
- Bipolar Transistors

## CMOS Technology



#### **NMOS** Transistor



#### **PMOS Transistor**



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### Today's CMOS Transistors



SiO<sub>2</sub> dielectric Polysilicon gate electrode Hafnium-based dielectric Metal gate electrode

SiGe

- Today's transistors have advanced device structures
- Most advanced transistors are moving from poly-gates back to metal-gates
  - Allows for High-K gate dielectric and reduced gate leakage current

[Bohr ISSCC 2009]

## Interconnect (Wires)

#### Loose pitch + thick metal on upper layers

- High speed global wires
- · Low resistance power grid

#### Tight pitch on lower layers

 Maximum density for local interconnects

[Bohr ISSCC 2009]



#### Diodes



Typical values:

P+=1017-1019 acceptors /cm3

P=10<sup>15</sup>-10<sup>17</sup> acceptors /cm<sup>3</sup>

N=10<sup>16</sup>-10<sup>18</sup> donors/cm<sup>3</sup>

N<sup>+</sup>=10<sup>17</sup>-10<sup>19</sup> donors/cm<sup>3</sup>

Metal  $\rightarrow$  5x10<sup>22</sup> electrons/cm<sup>3</sup>

#### Resistors



 Different resistor types have varying levels of accuracy and temperature and voltage sensitivities

#### Capacitors



## Inductors



- Inductors are generally too big for widespread use in analog IC design
  - Can fit thousands of transistors in a typical inductor area (100μm x 100μm)
- Useful to extend amplifier bandwidth at zero power cost (but significant area cost)

## Bipolar Transistors – Vertical PNP



Useful in a precise voltage reference circuit commonly implemented in ICs (Bandgap Reference)

## Bipolar Transistors – Latchup



- Potential for parasitic BJTs (Vertical PNP and Lateral NPN) to form a positive feedback loop circuit
- If circuit is triggered, due to current injected into substrate, then a large current can be drawn through the circuit and cause damage
- Important to minimize substrate and well resistance with many contacts/guard rings

### Next Time

- MOS Transistor Modeling
  - DC I-V Equations
  - Small-Signal Model